



Specifications

System Mainboard	OPS302
CPU Type	AMD R & G -Series 28nm Quad-Core/Dual-Core APU
CPU Package	FP4 BGA package, 37mm x 29mm, 0.8mm pitch
Chipset	AMD integrated Soc
Memory	2x DDR4-2133 SO-DIMM, dual channel, Max. 32 GB
Graphics	Next-gen AMD Radeon™ HD GPU integrated
LAN	1x Realtek RTL8111G Gigabit LAN controller
Expansion Slots	1x M.2 E-Key (2230) for Wi-Fi or Bluetooth options
I/O Interface	1x HDMI 1.4b 2x USB 3.0 2x USB 2.0 1x RJ45 for Gigabit LAN 1x RJ45 for RS232 serial port 2x audio connectors for Line-in / Line-out Power / HDD LED, 1x power on/off button
Auto Control and Monitoring	Watchdog Timer: 256 segments, 0, 1, 2...255 (sec/min)
Power Requirement	+12~19V DC
Construction	SGCC
Weight	0.9 kgs (1.98 lbs)
Chassis Color	Black and gray
Storage	1x M.2 M-Key (2280)
Power Supply	Power Requirement: DC-in +12V~+19V (Intel® OPS standard)
Mounting	OPS standard bracket
Dimensions	200mm(W) x 119mm(D) x 30mm(H) 7.87"(W) x 4.69"(D) x 1.18"(H)
Operating Temperature	0°C ~ 40°C (32°F ~ 104°F)
Storage Temperature	-20°C ~ 80°C (-4°F ~ 176°F)
Relative Humidity	5%~90% @45oC (non-condensing)
Vibration	SSD: 5 grms / 5~500Hz / random operation
Certification	CE, FCC class B
Operating System	Windows® 7 (32/64-bit), Windows 8.1† (64-bit) Windows 10 (64-bit), Windows 10 IoT Enterprise (64-bit) Windows Embedded Standard 7 (32/64-bit) Windows Embedded Standard 8 (32/64-bit) Linux Open Source (64-bit)

Features

- iSMART - for EuP/ErP power saving, auto-scheduling and power resume
- Supports 3rd Generation AMD Embedded R&G series APU.
- 2x DDR4-2133 SO-DIMM, dual channel, Max 32 GB.
- 1x HDMI
- 1x Line out / 1x Mic in
- 1x RJ45 for Gigabit LAN / 1x RJ45 for COM port
- 2x USB 3.0 ports ; 2x USB 2.0 ports
- 1x M.2 E-Key(2230) for Wi-Fi or Bluetooth options

Ordering Information

iOPS-302	OPS System with AMD GX-224IJ 2.4GHz APU, with 1x4 GB DDR4 2133 SO-DIMM memory, M.2 128GB storage
iOPS-DK1	iOPS-76/302/602 series Expansion Dock with 150W adaptor for use without OPS display

Dimensions

